

Refine Search

Search Results -

Terms	Documents
"first conductor" and "second terminal surface" and "third conductor" and "chip" and "resin package" and "third conductor"	2

Database:

US Pre-Grant Publication Full-Text Database

US Patents Full-Text Database
 US OCR Full-Text Database
 EPO Abstracts Database
 JPO Abstracts Database
 Derwent World Patents Index
 IBM Technical Disclosure Bulletins

Search:

L10

Search History

DATE: Friday, September 09, 2005 [Printable Copy](#) [Create Case](#)

<u>Set Name</u> side by side	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u> result set
	<i>DB=PGPB; PLUR=YES; OP=OR</i>		
<u>L10</u>	"first conductor" and "second terminal surface" and "third conductor" and "chip" and "resin package" and "third conductor"	2	<u>L10</u>
	<i>DB=JPAB; PLUR=YES; OP=OR</i>		
<u>L9</u>	"chip or die" and ("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	0	<u>L9</u>
	<i>DB=EPAB; PLUR=YES; OP=OR</i>		
<u>L8</u>	"chip or die" and ("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	0	<u>L8</u>
	<i>DB=USPT; PLUR=YES; OP=OR</i>		
<u>L7</u>	L6 and ((terminal or electrode) near15 ((chip or die) near8 ("upper surface" or "lower surface" or "first surface" or "second surface")))	77	<u>L7</u>
<u>L6</u>	L5 and (die or chip)	3111	<u>L6</u>

<u>L5</u>	L4 and ("third conductor" or "third terminal" or "third bonding pad" or "third electrode")	12883	<u>L5</u>
<u>L4</u>	L3 and ("second conductor" or "second terminal" or "second bonding pad" or "second electrode")	65101	<u>L4</u>
<u>L3</u>	("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	73858	<u>L3</u>
<u>L2</u>	"chip or die" and ("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	0	<u>L2</u>
<u>L1</u>	4945398	23	<u>L1</u>

END OF SEARCH HISTORY